

# **General Description**

The FDN8601 use advanced SGT MOSFET technology to provide low RDS(ON), low gate charge, fast switching and excellent avalanche characteristics.

This device is specially designed to get better ruggedness and suitable to use in

# D G G SOT-23-3L

#### **General Features**

 $V_{DS}$  =100V  $I_{D}$  =5 A

 $R_{DS(ON)}$  < 140m $\Omega$ @  $V_{GS}$ =10V



#### N-Channel MOSFET

## **Applications**

Consumer electronic power supply Motor control

Synchronous-rectification Isolated DC

Synchronous-rectification applications

## Package Marking and Ordering Information

Product ID	Pack	Brand	Qty(PCS)
FDN8601	SOT-23-3L	HXY MOSFET	3000

Absolute Maximum Ratings (T<sub>C</sub>=25<sup>°</sup>Cunless otherwise noted)

Symbol	Parameter	Rating	Units	
V <sub>DS</sub>	Drain-Source Voltage 100			
Vgs	Gate-Source Voltage ±20			
I <sub>D</sub> @T <sub>C</sub> =25°C	Continuous Drain Current, V <sub>GS</sub> @ 10V 5			
I <sub>D</sub> @T <sub>C</sub> =70°C	Continuous Drain Current, V <sub>GS</sub> @ 10V 2.2			
МП	Pulsed Drain Current <sup>2</sup> 11		А	
P <sub>D</sub> @T <sub>C</sub> =25°C	Total Power Dissipation <sup>4</sup> 1		W	
Тѕтс	Storage Temperature Range -55 to 150		°C	
TJ	Operating Junction Temperature Range -55 to 150		°C	
R <sub>θ</sub> JC	Thermal Resistance from Junction-to-Ambient <sup>3</sup>	ermal Resistance from Junction-to-Ambient <sup>3</sup> 80 °C.		
Reja	Thermal Resistance Junction-Ambient <sup>1</sup>	125	°C/W	



# **Electrical Characteristics** Tc=25℃ unless otherwise specified

Symbol	Parameter	Test Condition	Min.	Тур.	Max.	Units
Off Chara	cteristic		•			
V <sub>(BR)DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> = 0V, I <sub>D</sub> = 250μA	100	110	-	V
IDSS	Zero Gate Voltage Drain Current	V <sub>DS</sub> = 100V, V <sub>GS</sub> = 0V	-	-	1	μA
Igss	Gate to Body Leakage Current	V <sub>DS</sub> = 0V, V <sub>GS</sub> = ±20V	-	-	±100	nA
On Charac	cteristics note3					
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	1.0	1.95	3.0	V
R <sub>DS(on)</sub>	Static Drain-Source On-Resistance note2	V <sub>GS</sub> = 10V, I <sub>D</sub> = 3A	-	95	140	mΩ
Dynamic (	Characteristics note4		•			
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> = 50V, V <sub>GS</sub> = 0V, f = 1.0MHz	-	196	-	pF
Coss	Output Capacitance		-	25.9	-	pF
C <sub>rss</sub>	Reverse Transfer Capacitance		-	21.4	-	pF
Qg	Total Gate Charge	V <sub>DS</sub> = 50V, I <sub>D</sub> = 3A,	-	4.3	-	nC
Qgs	Gate-Source Charge		-	3.5	-	nC
Q <sub>gd</sub>	Gate-Drain("Miller") Charge	V <sub>GS</sub> = 10V	-	3.1	-	nC
Switching	Characteristics note4					
t <sub>d(on)</sub>	Turn-On Delay Time	V <sub>DD</sub> = 50V, I <sub>DS</sub> =3A	-	14.7	-	ns
tr	Turn-On Rise Time		-	3.5	-	ns
t <sub>d(off)</sub>	Turn-Off Delay Time	$R_G = 2\Omega$ , $V_{GEN} = 10V$	-	20.9	-	ns
t <sub>f</sub>	Turn-Off Fall Time		-	2.7	-	ns
Drain-Sou	rce Diode Characteristics and Maximum Rati	ngs	•	•		
Is	Maximum Continuous Drain to Source Diode Forward Current note2		-	-	4.5	Α
Ism	Maximum Pulsed Drain to Source Diode Forward Current		-	-	12	Α
V <sub>SD</sub>	Drain to Source Diode Forward Voltage note3	V <sub>GS</sub> = 0V, I <sub>S</sub> =3A	-	-	1.3	V
t <sub>rr</sub>	Body Diode Reverse Recovery Time	\/ - 0\/ I - 2A	-	32.1	-	ns
Qrr	Body Diode Reverse Recovery Time Charge	$V_{GS} = 0V, I_F = 3A,$	-	39.4	-	nC
Irrm	Peak Reverse Recovery Current	di/dt =100A/µs	-	2.1	-	Α

### Notes:

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- 2. Surface Mounted on FR4 Board, t ≤ 10 sec.
- 3. Pulse Test: Pulse Width ≤ 300μs, Duty Cycle ≤2%.
- 4. Guaranteed by design, not subject to production
- 5.  $V_{DD}$ =50 V,  $R_G$ =50  $\Omega$ , L=0.3 mH, starting  $T_j$ =25 °C



## **Typical Characteristics**

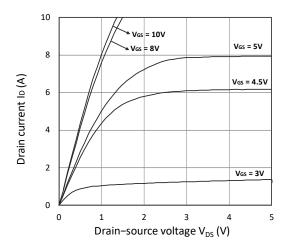


Figure 1. Output Characteristics

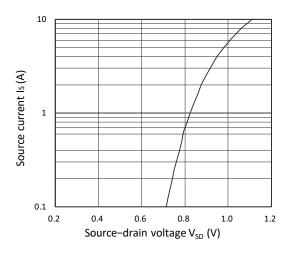


Figure 3. Forward Characteristics of Reverse

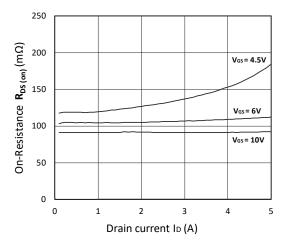


Figure 5.  $R_{DS(ON)}$  vs.  $I_D$ 

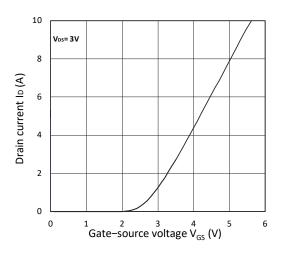


Figure 2. Transfer Characteristics

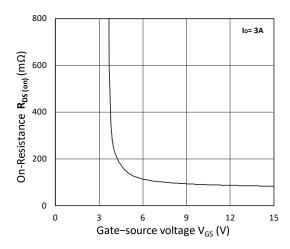


Figure 4.  $R_{\text{DS(ON)}}\,$  vs.  $V_{\text{GS}}\,$ 

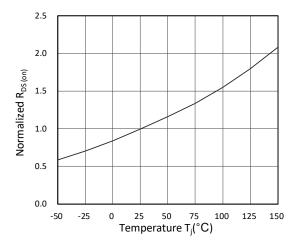


Figure 6. Normalized  $R_{\text{DS(on)}}$  vs. Temperature

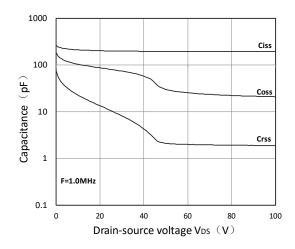


Figure 7. Capacitance Characteristics

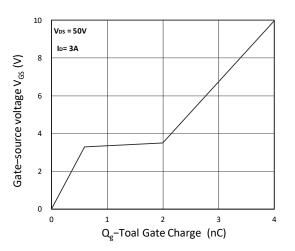
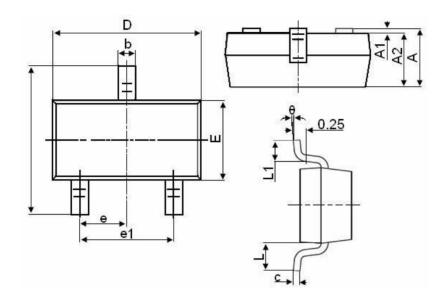


Figure 8. Gate Charge Characteristics

# **SOT-23-3L Package Information**



Symbol	Dimensions in Millimeters		
	MIN.	MAX.	
А	1.050	1.250	
A1	0.000	0.100	
A2	1.050	1.150	
b	0.300	0.500	
С	0.100	0.200	
D	2.800	3.000	
Е	1.500	1.700	
E1	2.650	2.950	
е	0.950TYP		
e1	1.800	2.000	
L	0.550REF		
L1	0.300	0.600	
θ	0°	8°	



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